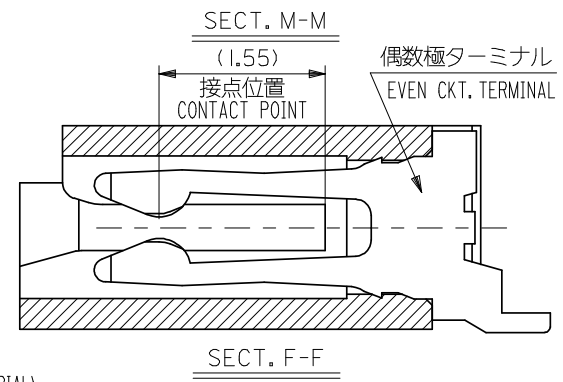
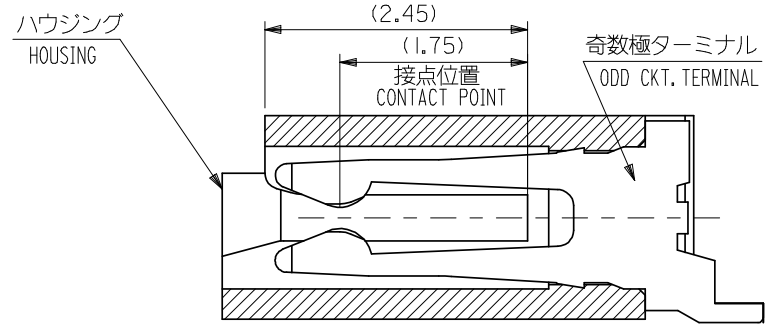
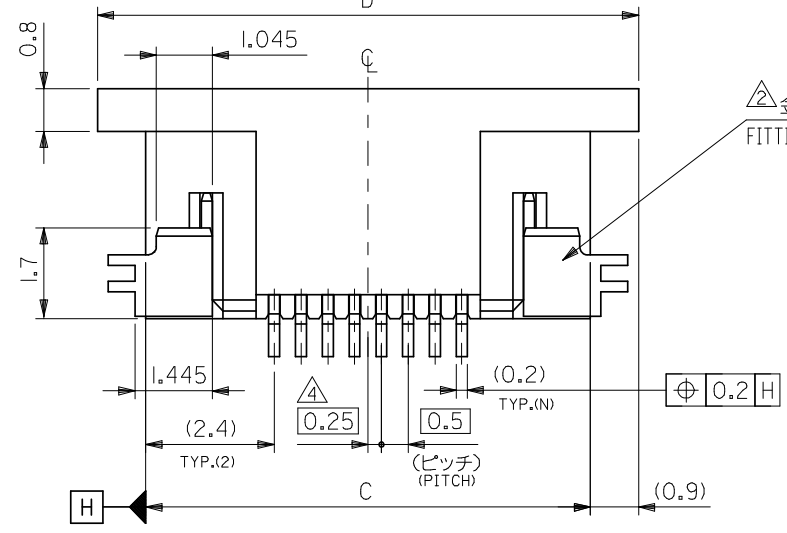


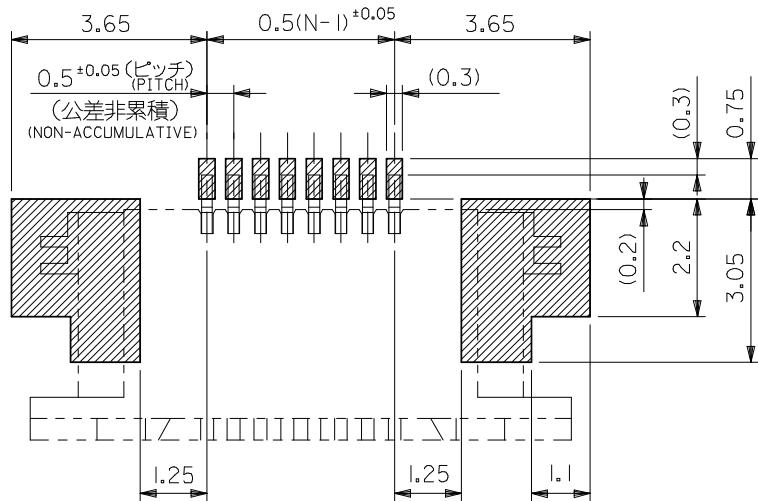
△ 金具  
FITTING NAIL



注記(NOTES)

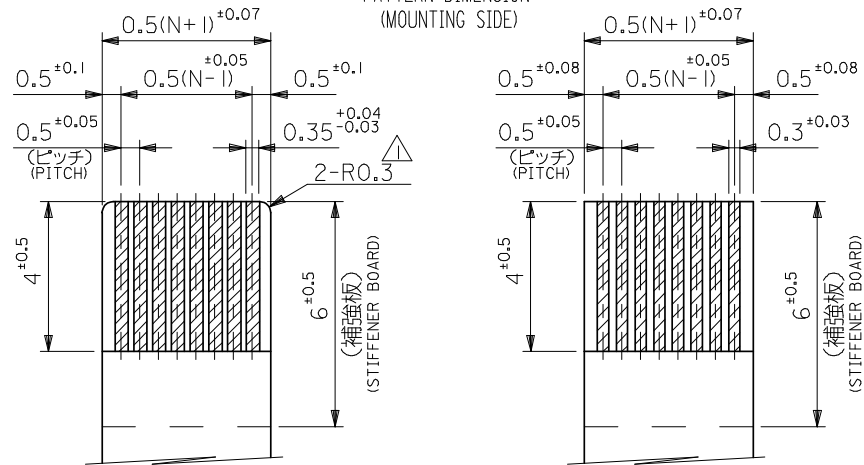
1. 使用材料 (MATERIAL)  
ターミナル (TERMINAL): リン青銅  
PHOSPHOR BRONZE t=0.2  
鍍ビスマスメッキ 1. 0マイクロメートル以上  
TIN-BISMUTH I.O. MICROMETER MINIMUM  
ニッケル下地 1. 0マイクロメートル以上  
NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM  
ハウジング (HOUSING): 46ナイロン (46NYLON), UL94V-0  
金具 (FITTING NAIL): リン青銅  
PHOSPHOR BRONZE t=0.2  
鍍メッキ 1. 0マイクロメートル以上  
TIN I.O. MICROMETER MINIMUM  
ニッケル下地 1. 0マイクロメートル以上  
NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM
- △ パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)  
ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX.、下方向 0.15MAX. とする。  
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L  
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
- △ 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
5. 本製品は 52689-\*\*\*40 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE 52689-\*\*\*40.

REVISED EC NO: J2008-4308 DRWN: MWABEI CHKD: THARUYAMA APPR: NUKITA	DESCRIPTION 2008/06/27 2008/06/30 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		---	METRIC			
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE				
		10 OVER 30 UNDER	±0.25	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-				
		30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED				
ANGULAR	±3	APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2		M. SASAO		SD-52689-034		1 OF 2		
		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
		A3								



参考基板レイアウト  
(マウント面)

REFERENCE P.C.BOARD  
PATTERN DIMENSION  
(MOUNTING SIDE)



適合F P C推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION

(仕上がり厚さ:  $0.3 \pm 0.03$ )  
(THICKNESS:  $0.3 \pm 0.03$ )

適合F F C推奨寸法  
APPLICABLE FFC  
RECOMMENDED DIMENSION

(仕上がり厚さ:  $0.3 \pm 0.03$ )  
(THICKNESS:  $0.3 \pm 0.03$ )

FPCについて:  
打抜き方向は導体側から補強板側を推奨致します。  
補強フィルム材質はポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:  
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。  
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

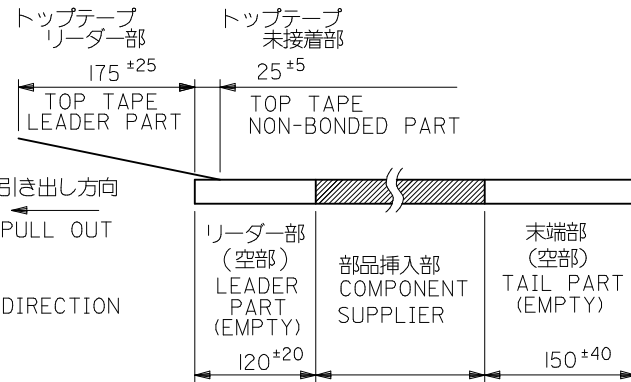
17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
17.1	20.6	18.8	15.0	14.0	-2987	-2949	29
16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
16.1	19.6	17.8	14.0	13.0	-2787	-2749	27
15.6	19.1	17.3	13.5	12.5	-2687	-2649	26
15.1	18.6	16.8	13.0	12.0	-2587	-2549	25
14.6	18.1	16.3	12.5	11.5	-2487	-2449	24
14.1	17.6	15.8	12.0	11.0	-2387	-2349	23
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
13.1	16.6	14.8	11.0	10.0	-2187	-2149	21
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
12.1	15.6	13.8	10.0	9.0	-1987	-1949	19
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
9.6	13.1	11.3	7.5	6.5	-1487	-1449	14
9.1	12.6	10.8	7.0	6.0	-1387	-1349	13
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
8.1	11.6	9.8	6.0	5.0	-1187	-1149	11
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
7.1	10.6	8.8	5.0	4.0	-0987	-0949	9
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSSED TAPE	MATERIAL NO.	極数 CKT.
MODEL NO.						ORDER No. オーダー番号		

REVISED EC NO: J2008-4308 DRWN:WABEI 2008/06/27 CHKD:THARUYAMA 2008/06/30 APPR:NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/03	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/02/03	DOCUMENT NO. SD-52689-034			
	ANGULAR	±3 °	MATERIAL NO.	SEE TABLE	SHEET NO. 2 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

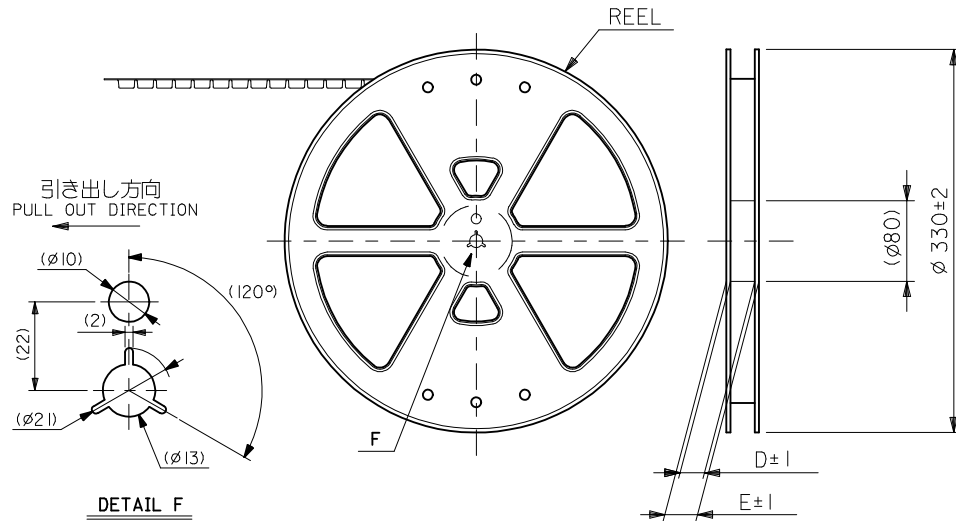
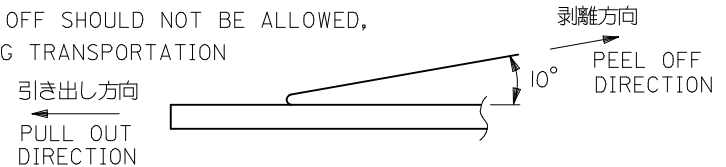
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。  
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール  
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)  
0.1~1.3N {10~130gf}  
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE  
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
PEEL OFF SHOULD NOT BE ALLOWED,  
DURING TRANSPORTATION



- 材料  
キャリアテープ：ポリプロピレン (PP)  
トップテープ：PET, PE, PEF  
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE  
TOP TAPE:PET,PE,PEF  
REEL:POLYSTYREN(PS)  
<RECYCLE MATERIAL CONTAINED>

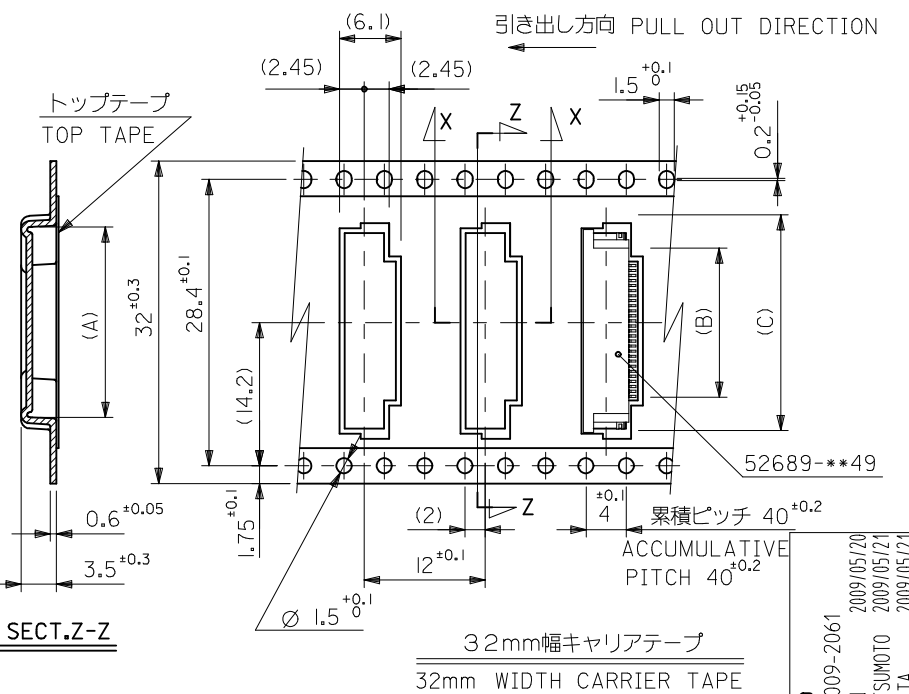
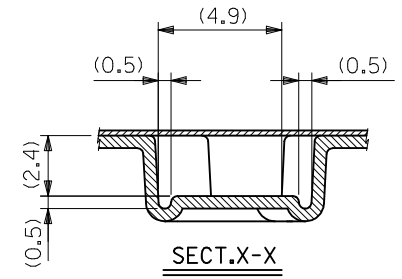
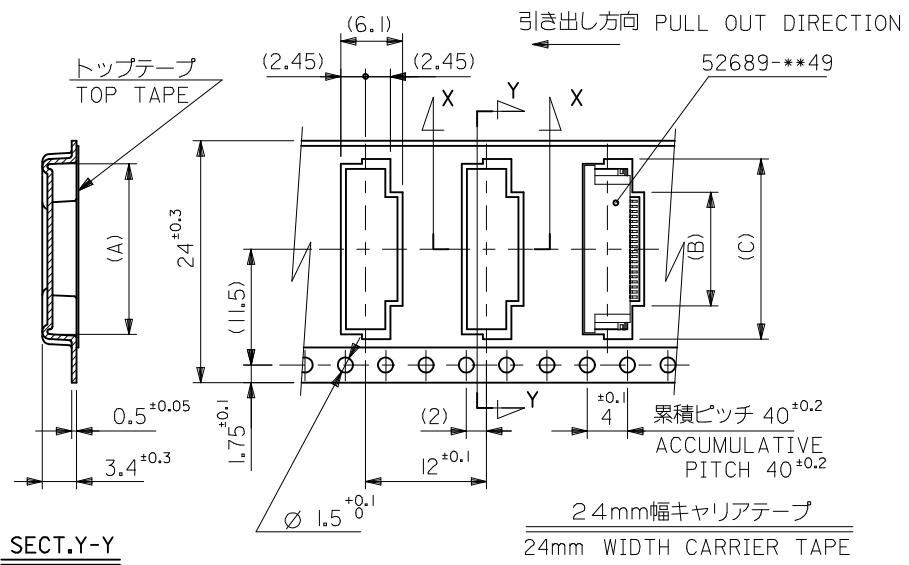
- 本製品は52689-\*\*\*93の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 52689-\*\*\*93.

- FPCについて：  
打抜き方向は導体側から補強板側を推奨致します。  
補強フォルム材質はポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:  
RECOMMENDED PUNCHER DIRECTION :  
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

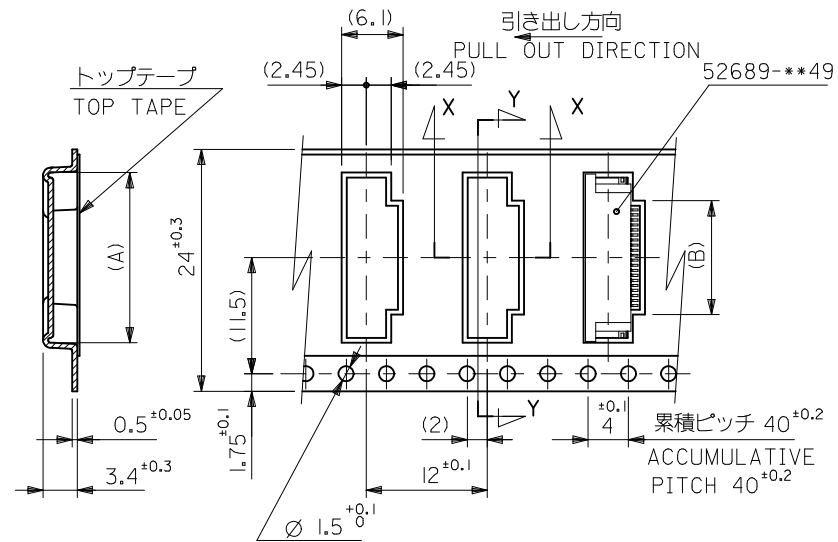
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO.: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HATSUMOTO 2009/05/21 APPR:NIKIITA 2009/05/21 REV: A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOJO	DATE 2004/02/03	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M.SASAO	DATE 2004/02/03	DOCUMENT NO. SD-52689-035	SHEET NO. 1 OF 3	
	ANGULAR ±3°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 2,3			
		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

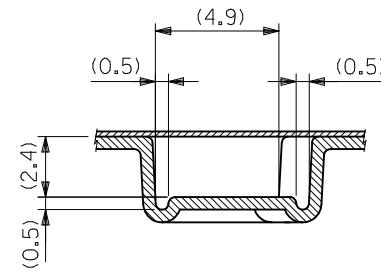


32	37.4	33.4	22.4	15.8	21.4	52689 -3087	30
			21.9	15.3	20.9	-2987	29
			21.4	14.8	20.4	-2887	28
			20.9	14.3	19.9	-2787	27
			20.4	13.8	19.4	-2687	26
			19.9	13.3	18.9	-2587	25
			19.4	12.8	18.4	-2487	24
			18.9	12.3	17.9	-2387	23
			17.9	11.3	16.9	-2187	21
			17.4	10.8	16.4	-2087	20
24	29.4	25.4	16.9	10.3	15.9	-1987	19
			16.4	9.8	15.4	-1887	18
			15.4	8.8	14.4	-1687	16
			14.9	8.3	13.9	-1587	15
			14.4	7.8	13.4	-1487	14
			13.9	7.3	12.9	-1387	13
			13.4	6.8	12.4	-1287	12
			12.9	6.3	11.9	-1187	11
			12.4	5.8	11.4	-1087	10
			11.9	5.3	10.9	-0987	9
11.4	4.8	10.4	-0887	8			
10.9	4.3	9.9	-0787	7			
10.4	3.8	9.4	-0687	6			
9.9	3.3	8.9	52689 -0587	5			

REVISED	EC NO: J2009-2061	2009/05/20	DRWN:TKON	2009/05/21	CHKD:HATSUMOTO	2009/05/21	APPR:NIKIITA	2009/05/21
DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)							
REV	10 UNDER	±0.2	10 OVER 30 UNDER	±0.25	30 OVER	±0.3	ANGULAR	±3°
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							
	MODEL NO.	52689-**-87	CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)
	DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
	MM ONLY		---		METRIC		☉	
	DRAWN BY	DATE	TITLE					
	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-					
	CHECKED BY	DATE	MATERIAL NO.					
	K.TOJO	2004/02/03	SEE TABLE					
	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.			
	M.SASAO	2004/02/03	SD-52689-035		2 OF 3			
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE



SECT.X-X

24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅	E	D	(B)	(A)	MATERIAL NO.
MODEL NO.	CARRIER TAPE WIDTH					極数 CIRCUIT

REVISED EC NO: J2009-2061 DRWN:TKON CHKD:HMATSUMOTO APPR:NUKITA	DESCRIPTION 2009/05/20 2009/05/21 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
				MM ONLY		---		METRIC			
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE					
		10 OVER 30 UNDER	±0.25	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-					
30 OVER	±0.3	CHECKED BY	DATE								
ANGULAR ±3°		APPROVED BY		DATE		MOLEX INCORPORATED		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		M.SASAO		2004/02/03		SEE TABLE		SD-52689-035		3 OF 3	
		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							